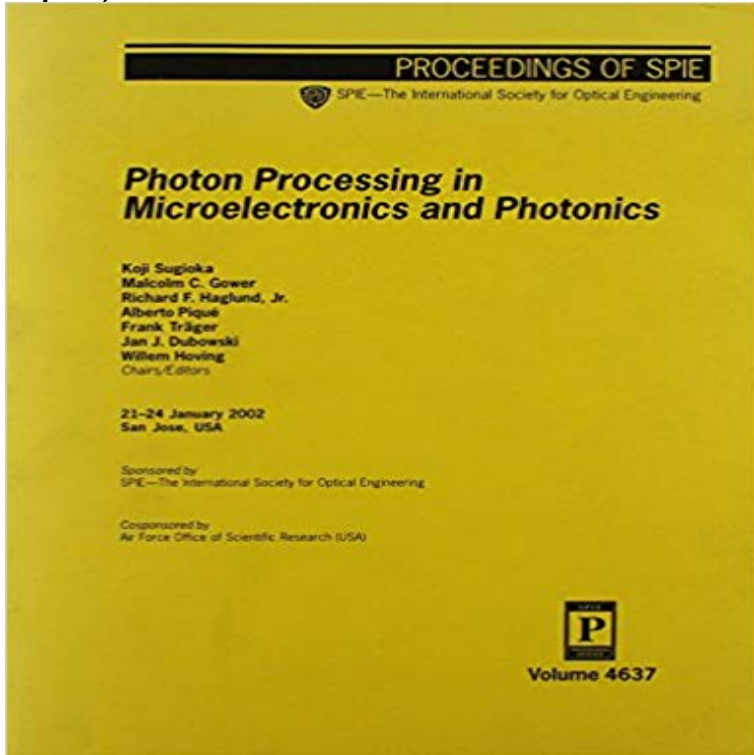


# Photon Processing in Microelectronics and Photonics (Proceedings of Spie)



Book by Sugioka, Koji, Gower, Malcolm C., Haglund, Richard F., Jr., Pique, Alberto

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